## NSN 5962-01-287-2391

Memory Microcircuit - Page 1 of 1



View Online at https://aerobasegroup.com/nsn/5962-01-287-2391 **Body Length:** Between 1.380 inches and 1.420 inches **Body Width:** Between 0.560 inches and 0.600 inches **Body Height:** Between 0.040 inches and 0.180 inches **Maximum Power Dissipation Rating:** 1.0 watts **Operating Tempurature Range:** -55.0/+125.0 degrees celsius Storage Tempurature Range: -65.0/+155.0 degrees celsius **Features Provided:** Electrostatic sensitive and hermetically sealed and burn in and monolithic **Inclosure Material:** Ceramic **Inclosure Configuration:** Dual-in-line **Output Logic Form:** Complementary-metal oxide-semiconductor logic **Input Circuit Pattern:** 14 input **Terminal Surface Treatment:** Solder Voltage Rating And Type Per Characteristic: -0.5 volts power source and 7.0 volts power source **Time Rating Per Chacteristic:** 140.00 nanoseconds propagation delay time, low to high level output and 140.00 nanoseconds propagation delay time, high to low level output **Memory Device Type:** Rom **Test Data Document:** 96906-mil-std-883 standard (includes industry or association standards, individual manufactureer standards, etc.). **Terminal Type And Quantity:** 28 printed circuit Shelf Life: N/a **Unit Of Measure:** 

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**Demilitarization:** Yes - demil/mli